

THERMAL DISSIPATING ELEMENT OF A CHIP

The present invention relates to a thermal
5 dissipating element of a chip to dissipate heat producing
by operating the chip. The thermal dissipating element
includes a cover and a lump. The cover includes a top
plate and a side plate, wherein the top plate curves and
extendedly connects to the side plate. The lump is
10 fastened between the chip and the top plate of the cover.